

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE PATENT APPLICATION OF:	JE A GUN PARK, ET AL.
SERIAL NO.:	10/540,992
ATTORNEY DOCKET NO.:	061063-0316598
FILING DATE:	June 5, 2006
CONFIRMATION NO.	9014
ART UNIT:	1792
EXAMINER:	ANGADI, Maki A.
FOR:	CHEMICAL-MECHANICAL-POLISHING SLURRY COMPOSITION, METHOD FOR PLANARIZING SURFACE OF SEMICONDUCTOR DEVICE USING THE SAME, AND METHOD FOR CONTROLLING SELECTION RATIO OF SLURRY COMPOSITION

AMENDMENT UNDER 37 C.F.R. § 1.111

Mail Stop Non-Fee Amendments

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Non-Final Office Action mailed June 4, 2009, the date for responding being September 4, 2009, please amend the above-identified application as follows:

Amendments to the claims begin on page 2 of this paper.

Remarks/Arguments begin on page 6.

It is believed that no extensions of time or fees for net addition of claims are required beyond those that may otherwise be provided for in documents accompanying this paper. However, if additional extensions of time are necessary to prevent abandonment of this application, then such extensions of time are hereby petitioned for under 37 C.F.R. § 1.136(a), and any fees required therefore (including fees for net addition of claims) are hereby authorized to be charged to our Deposit Account No. 033975 (Ref. No. 061063-0316598):.